

Title (en)

HEAT SINK FOR INTEGRATED CIRCUIT PACKAGES

Title (de)

WÄRMESENKE FÜR INTEGRIERTE SCHALTUNGSPACKUNGEN

Title (fr)

RADIATEUR POUR BOITIERS DE CIRCUITS INTEGRES

Publication

EP 0758488 A1 19970219 (EN)

Application

EP 96910413 A 19960306

Priority

- US 9603282 W 19960306
- US 39917395 A 19950306

Abstract (en)

[origin: WO9627903A1] A heat sink (52) for use in a molded integrated circuit package (38) includes a main body (54) formed of a thermally conductive material. The main body (54) has (i) an upwardly facing horizontally extending top surface (56) adapted to support either directly or indirectly an integrated circuit die (40), (ii) a downwardly facing horizontally extending bottom surface (58), (iii) an outer circumferential edge (60), and (iv) a slot (62) or recess (84) formed into the main body (54) of said heat sink (52). The slot (62) or recess (84) is adapted to receive some of an encapsulating material (50) during the molding of the integrated circuit package (38) so as to form a mechanical connection between the heat sink (52) and the package (38). And, the bottom surface (58) of the heat sink (52) is exposed on an external surface of the integrated circuit package (38) after the molding of the integrated circuit package (38) is complete.

IPC 1-7

H01L 23/433

IPC 8 full level

H01L 23/433 (2006.01)

CPC (source: EP KR)

H01L 23/433 (2013.01 - KR); **H01L 23/4334** (2013.01 - EP); **H01L 24/48** (2013.01 - EP); **H01L 2224/48091** (2013.01 - EP);
H01L 2224/48247 (2013.01 - EP); **H01L 2224/48465** (2013.01 - EP); **H01L 2924/00014** (2013.01 - EP); **H01L 2924/01013** (2013.01 - EP);
H01L 2924/01029 (2013.01 - EP); **H01L 2924/14** (2013.01 - EP); **H01L 2924/181** (2013.01 - EP)

Citation (search report)

See references of WO 9627903A1

Designated contracting state (EPC)

DE FR GB

DOCDB simple family (publication)

WO 9627903 A1 19960912; EP 0758488 A1 19970219; KR 970703045 A 19970610

DOCDB simple family (application)

US 9603282 W 19960306; EP 96910413 A 19960306; KR 19960706107 A 19961029